

Conforming Lid Socket for Leaded Surface Mount Packages

Abstract

The effects of the invention *Conforming Lid Socket* are accomplished by the use of a firm lid with conforming surface which presses the package leads towards contacts (pads) on the contact plate. The plate can be a rigid substrate with contacts and pins, a rigid printed circuit board or even flexible printed circuit board. The package leads are placed directly on those contacts (pads) pads. The lid is firm, with conforming surface at the compression points, hence it can compensate for varying thickness of individual leads and can guarantee sufficient pressure on every lead individually. A support plate may be required for the use on normal thickness rigid printed circuit boards, and is necessary for the use on flexible printed circuit boards. The need for the use of the support plate is based upon the stiffness of the contact plate and the size of the package.